

Device and Method for Embossing Micro- and/or Nanostructures

A b s t r a c t

The present invention relates to a device (1) for embossing structures into an embossing material, having a structure punch (4, 4', 4'', 4''', 4iv, 4v, 4vi, 4vii, 4viii) for embossing the structures into the embossing material, characterized in that the structure punch (4, 4', 4'', 4''', 4iv, 4v, 4vi, 4vii, 4viii) can be kept under a constant local expansion during ebossing and separation from the embossing material.

Fig. 1